

Job: 22186
Engr: rknorr

Customer: Concisys
Part No.: 22186
Part Rev: C

Stackup & Impedance

Laminate Type Auto
Minimum Tg 180
Min Td 360
MOT 0
PLC Code 0
T260 Min 0
T288 Min 0
Slash Sheet
Laminate Color Natural

Layer	Thickness (Inch)	Stackup Picture	Family	Description	Type
compmask	0.0010		SM-Std	SM-Std	
compside	0.0021		Cu-Std	.5 + Std + C2 Wrap	comp - Cu-Std
	0.0052		FR408HR	1080	
			FR408HR	106	
layer2	0.0006		Cu-Std	.5	plane_t
	0.0025		FR408HR	0.0025	
layer3	0.0006		Cu-Std	.5	plane_b
	0.0027		FR408HR	1080	
layer4	0.0006		Cu-Std	.5	plane_t
	0.0100		FR408HR	0.0100	
layer5	0.0021		Cu-Std	.5 + Std + C2 Wrap	plane_b
	0.0101		FR408HR	3313	
			FR408HR	3313	
			FR408HR	3313	
layer6	0.0021		Cu-Std	.5 + Std + C2 Wrap	signal_t
	0.0100		FR408HR	0.0100	
layer7	0.0006		Cu-Std	.5	signal_b
	0.0026		FR408HR	1080	
layer8	0.0006		Cu-Std	.5	signal_t
	0.0025		FR408HR	0.0025	
layer9	0.0006		Cu-Std	.5	signal_b
	0.0051		FR408HR	106	
			FR408HR	1080	
solderside	0.0021		Cu-Std	.5 + Std + C2 Wrap	solder - Cu-Std
soldermask	0.0010		SM-Std	SM-Std	

0.0648 Total Expected Thickness

0.0580 After Lamination

+0.0035 -0.0035

Drill/Rout Files: A: vias

B: plated

C: plated_x5

D: plated_6x

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Requirements Information in Inches

Top Layer	Bottom Layer	Required Thickness	Tol +	Tol -	Calculated Thickness
Incl.Plating		0.0620	0.0050	0.0050	0.0628
After Lamination		0.0580	0.0035	0.0035	0.0598
Manufactured Part	SubAssembly layer6 / x	0.0000			0.0263
Manufactured Part	SubAssembly x / layer5	0.0000			0.0264

Comments

Concise Impedance Constraint Information

Line Widths in Inches

#	Impedance Type	Aff Layer	Designed Width	Edited Width	Cntr to Cntr	Spacing	Ref Planes	Target ohms	Predicted ohms
1	Surface MS 	compside	0.01	0.01			None layer2	50 +/- 5.0	49.63
2	Surface MS 	solderside	0.01	0.01			None layer9	50 +/- 5.0	49.59
3	EC Microstrip 	compside	0.008	0.008	0.018	0.01	None layer2	100 +/- 10.0	98.50
4	EC Microstrip 	solderside	0.008	0.008	0.018	0.01	None layer9	100 +/- 10.0	98.44